

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –
Partie 1: Vue d'ensemble**



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FIELD DEVICE INTEGRATION (FDI) –

Part 1: Overview

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/337/CDV	65E/421/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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INTRODUCTION

The IEC 62657 series has the general title "Field Device Integration (FDI)" and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
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FIELD DEVICE INTEGRATION (FDI) –

Part 1: Overview

1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62453 (all parts), *Field device tool (FDT[®]) interface specification*

IEC 62541 (all parts), *OPC Unified Architecture*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE IEC 62769-2 is technically identical to FDI-2022[4]¹

IEC 62769-3, *Field Device Integration (FDI) – Part 3: FDI Server*

NOTE IEC 62769-3 is technically identical to FDI-2023. [5]

IEC 62769-4:2015, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE IEC 62769-4 is technically identical to FDI-2024. [6]

IEC 62769-5:2015, *Field Device Integration (FDI) – Part 5: FDI Information Model*

¹ Numbers in square brackets refer to the Bibliography.